IEEE International
3D Systems Integration Conference
3DIC 2026

October 1-2, 2026

Call for Papers

The IEEE International 3D Systems Integration Conference is a peer-reviewed conference that aims to bring together 3D researchers from academia, government, and industry. 3DIC 2026 invites high-quality novel research paper submissions that focus on 3D methodological and application perspectives.

Location: This year's IEEE International 3D System Integration Conference (3DIC 2026) will be held at **Georgia Institute of Technology, Atlanta.**

Topics Areas:

Papers are solicited on all 3D IC topics including, but not limited to, the following:

> **Technology:** Materials, equipment, wafer handling, diverse substrates, Through Silicon Vias (TSV), alignment, bonding (thermo-compression, electrostatic, hybrid, temporary adhesive), de-bonding, wafer cleaning, thinning, dicing, chiplets, interposers (active, passive), 3D integration (monolithic, heterogeneous), capacitive coupling, inductive coupling, multilevel epitaxial growth, etc.
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> **Applications, Design and Computer Aided Design (CAD):** Synthesis, design flows, signal design, power integrity, thermal considerations, mechanical stress, reliability, test, techniques, analysis, chiplet and chiplet design etc. Applications to be considered may include imaging, memory, processors, communications, networking, wireless, biomedical, sensors, SOC, MEMS, DSP, FPGA, RF, microwave, millimeter wave, analog circuits, biomedical circuits, photonics, optoelectronics, etc. Application areas such quantum computing, embedded systems, artificial intelligence and others.

Paper Submissions:

- **Extended Deadline:** Presentation abstracts may be submitted on the conference website through September 1, 2026.
- **Submission and Registration Website:** www.3dic-conf.org.
- **Length and Format:** Abstracts should be about 500 words in length; some figures and tables can be included. Notifications will occur by September 14. Full papers in camera-ready IEEE format are required by September 29, 2026.

Workshop and Tutorials:

3DIC 2026 seeks high quality workshop and tutorial proposals in the areas of 3D integration technology, applications, design, and computer aided design. To propose an idea for a tutorial please contact the conference organizers at 3dic@gatech.edu .